

TOREX SEMICONDUCTOR LTD.
Quality Assurance Dept.

Composition Table

Product(Pb-free): XC9247xxxxMR-G
Typical Mass: 17 mg

Part name	Weight(mg)	Material name	Ratio(ppm)	CAS number
Silicon chip	0.606	Silicon	35600	7440-21-3
	-	Arsenic	<1	7440-38-2
Leadframe	6.358	Copper	374000	7440-50-8
	0.080	Iron	4700	7439-89-6
	0.016	Zinc	900	7440-66-6
	0.013	Chromium	800	7440-47-3
	0.012	Tin	700	7440-31-5
	0.003	Phosphorus	200	7723-14-0
	0.262	Silver	15400	7440-22-4
Die attach	0.042	Silver	2500	7440-22-4
	0.010	Epoxy resin	600	—
	0.002	Phenol resin	100	—
Bonding wire	0.185	Gold	10900	7440-57-5
Resin	7.679	Silica	451700	60676-86-0
	0.789	Epoxy resin	46400	—
	0.395	Phenol resin	23200	—
	0.130	Metal hydroxide	7600	—
Plating	0.421	Tin	24800	7440-31-5

* The component composition is based on the information provided by raw material vender.

* The mass of the IC and its fractions could be different due to the manufacturing conditions of materials.

* Any indication "-" in CAS number means "confidential."